

具有同步和电源正常指示功能的 TPS40195 4.5V 至 20V 同步降压控制器

1 特性

- 输入工作电压范围：4.5V 至 20V
- 输出电压低至 0.591V $\pm$ 0.5%
- 180° 双向异相同步功能
- 内部 5V 稳压器
- 高侧和低侧过流检测 MOSFET
- 100kHz 至 600kHz 开关频率
- 使能引脚和电源正常指示功能
- 可编程 UVLO 与迟滞功能
- 150°C 时进行热关断
- 可选软启动
- 预偏置输出安全保护

2 应用

- 数字电视
- 入门级和中端服务器
- 网络设备
- 非隔离式直流/直流模块

3 说明

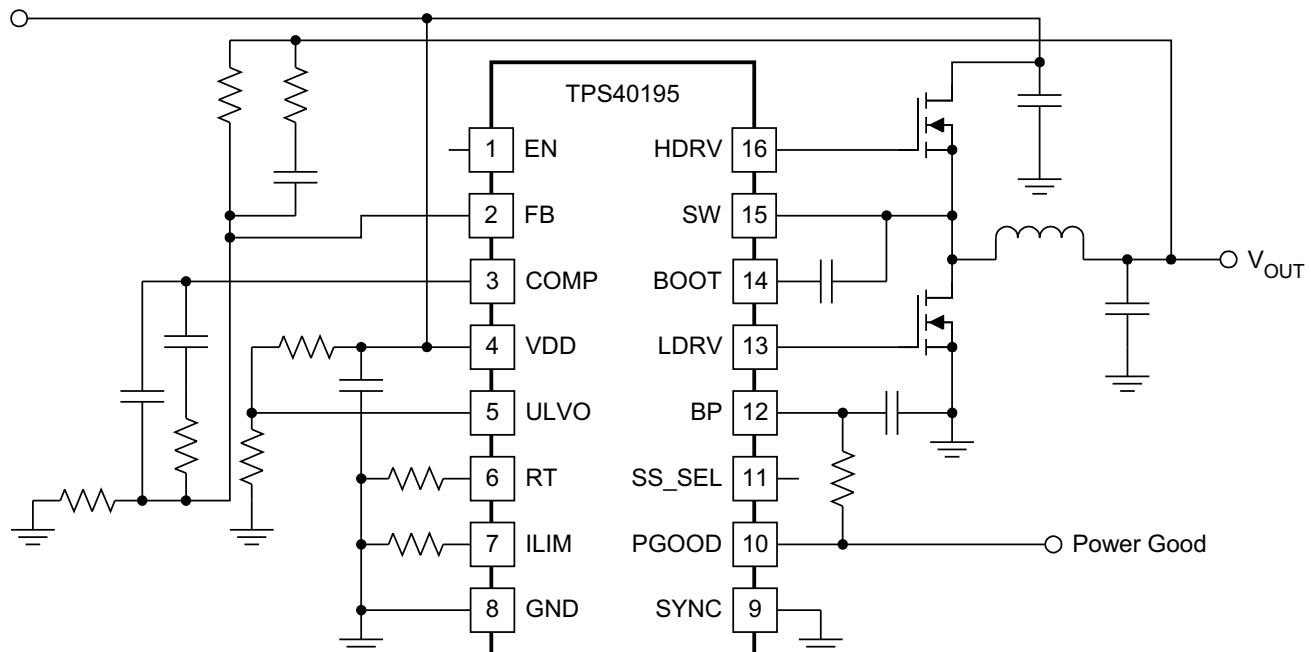
TPS40195 是一款灵活的同步降压控制器，可在额定 4.5V 至 20V 的电源下工作。此控制器通过在 100kHz 至 600kHz 范围内可调的开关频率来实施电压模式控制。此器件的灵活功能包括可选软启动时间、可编程短路限制、可编程欠压锁定 (UVLO) 和同步功能。自适应反跨导方案可用于防止功率 FET 中产生击穿电流。通过检测低侧 MOSFET（打开时）上的压降并将其与用户编程的阈值进行比较，来实现过流检测。

器件信息⁽¹⁾

器件型号	封装	封装尺寸（标称值）
TPS40195	TSSOP (16)	5.00mm $\times$ 4.40mm
	VQFN (16)	4.00mm $\times$ 3.50mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

简化应用示意图



UDG-06066



目录

1	特性	1	6.2	器件支持	4
2	应用	1	6.3	文档支持	4
3	说明	1	6.4	接收文档更新通知	4
4	修订历史记录	2	6.5	社区资源	4
5	说明（续）	3	6.6	商标	4
6	器件和文档支持	4	6.7	静电放电警告	5
6.1	器件支持	4	6.8	Glossary	5
7	机械、封装和可订购信息	5			

4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision E (July 2012) to Revision F	Page
• 仅有编辑更改；无技术性修订	1
• 添加了 <i>ESD</i> 额定值表、特性说明部分、器件功能模式、应用和实施部分、电源建议部分、布局部分、器件和文档支持部分以及机械、封装和可订购信息部分。	1
• 删除了可订购信息表	1

Changes from Revision D (November 2008) to Revision E	Page
---	------

5 说明（续）

该阈值可通过从 ILIM 连接到 GND 的单个外部电阻器进行设置。通过检测高侧 MOSFET（通电时）上的电压并在压降上升超过 550mV 固定阈值时终止周期来提供逐脉冲限流功能（以防止电流失控）。如果控制器检测到输出短路，则会关闭两个 MOSFET，并在达到超时时间后尝试重启。这能在持续故障情况下实现有限的功率耗散。此器件上的同步功能是双向的。器件可 180° 异相同步至选定主器件 TPS40195（在固定频率 250kHz 或 500kHz 上运行），也可以同步至外部时钟源（100kHz 至 600kHz 范围内的任意频率）。

6 器件和文档支持

6.1 器件支持

6.1.1 第三方产品免责声明

TI 发布的与第三方产品或服务有关的信息，不能构成与此类产品或服务或保修的适用性有关的认可，不能构成此类产品或服务单独或与任何 TI 产品或服务一起的表示或认可。

6.2 器件支持

6.2.1 相关器件

以下器件具有与 TPS40195 相似的特性，您可能对此感兴趣。

表 1. 相关器件

器件	说明
TPS40100	中端输入同步控制器，具有高级排序功能和输出裕量
TPS40075	具有电压前馈功能的宽输入同步控制器
TPS40190	低引脚数同步降压控制器
TPS40192/3	具有电源正常指示功能的 4.5V 至 18V 输入、低引脚数同步降压控制器

6.3 文档支持

6.3.1 相关文档

如需查看这些参考资料，请访问 www.power.ti.com 网站的“技术文档”页面。此外还有众多设计工具和其他参考（包括设计软件），其链接位于 www.power.ti.com。

- 《低电压直流/直流转换器内幕揭秘》，SEM 1500 Topdevice 5，2002 年系列研讨会
- 《了解开关模式电源中的降压功率级》，SLVA057，1999 年 3 月
- 《高速 MOSFET 栅极驱动电路的设计和应用指南》，SEM 1400，2001 年系列研讨会
- 《设计稳定控制环路》，SEM 1400，2001 年系列研讨会
- 有关 PowerPAD™ 的更多信息，请参阅《应用 简介》SLMA002 和 SLMA004
- 《QFN/SON PCB 连接》，德州仪器 (TI) 文献编号 SLUA271，2002 年 6 月

6.4 接收文档更新通知

要接收文档更新通知，请导航至 Ti.com.cn 上的器件产品文件夹。单击右上角的通知我 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

6.5 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.6 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

6.7 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

6.8 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

7 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS40195PW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	40195
TPS40195PW.A	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	40195
TPS40195PWG4	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	40195
TPS40195PWG4.A	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	40195
TPS40195PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	40195
TPS40195PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	40195
TPS40195RGYR	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	40195
TPS40195RGYR.A	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	40195
TPS40195RGYT	Active	Production	VQFN (RGY) 16	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	40195
TPS40195RGYT.A	Active	Production	VQFN (RGY) 16	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	40195
TPS40195RGYTG4	Active	Production	VQFN (RGY) 16	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	40195

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

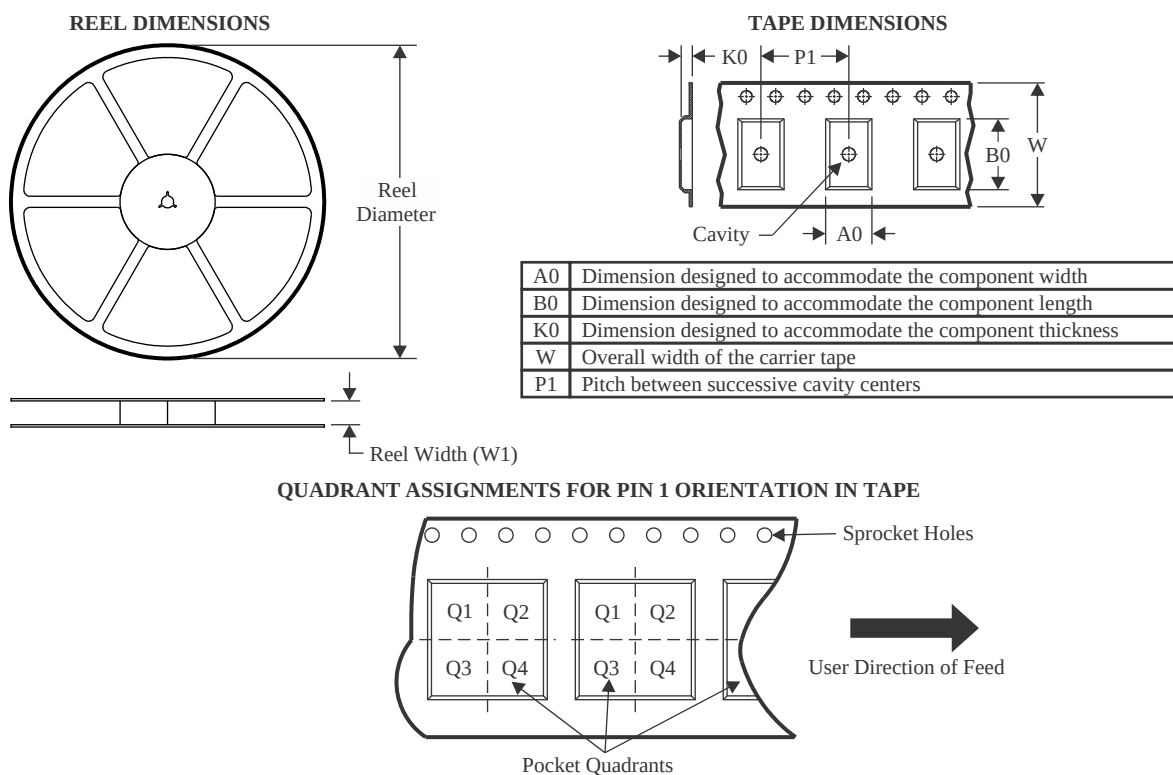
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

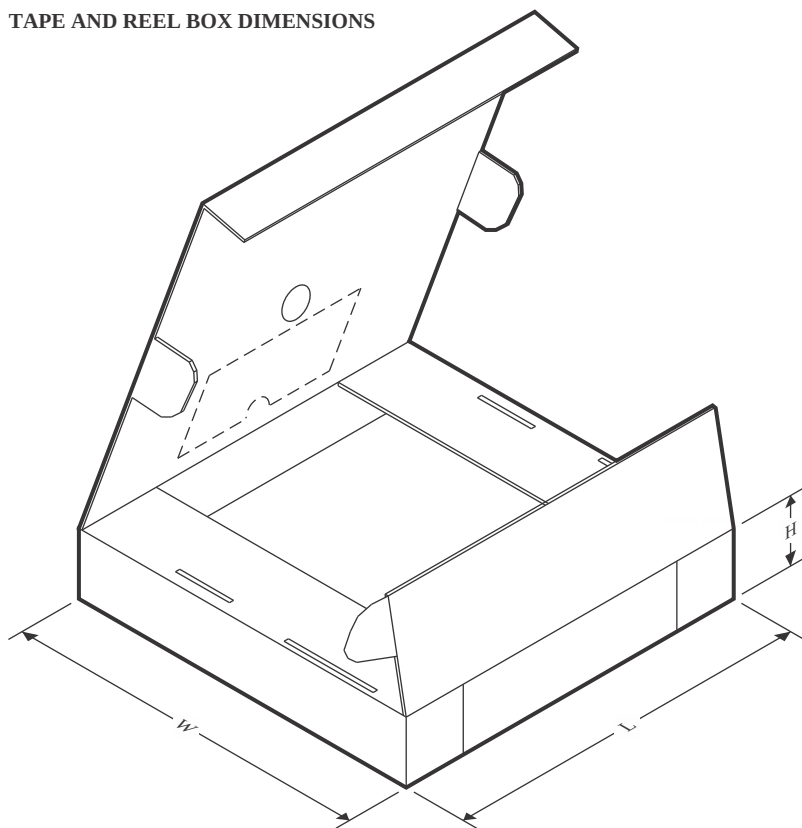
TAPE AND REEL INFORMATION



*All dimensions are nominal

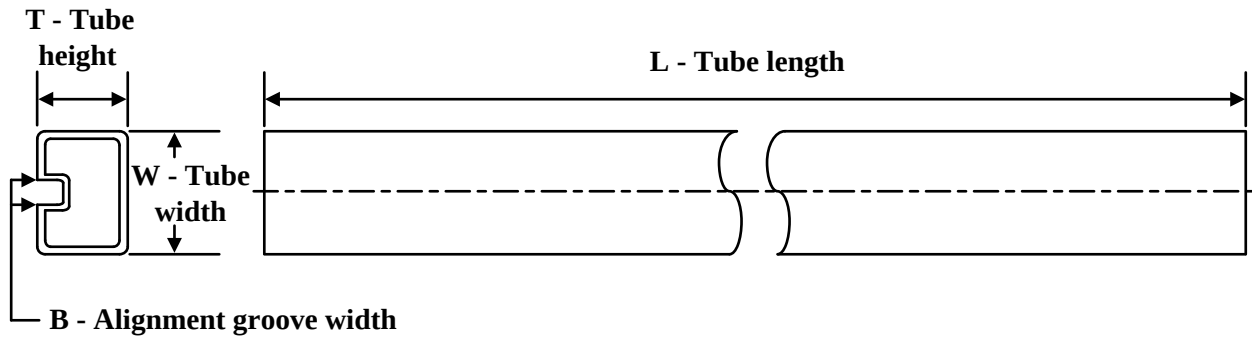
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS40195PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TPS40195RGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1
TPS40195RGYR	VQFN	RGY	16	3000	330.0	12.4	3.71	4.21	1.11	8.0	12.0	Q1
TPS40195RGYT	VQFN	RGY	16	250	180.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1
TPS40195RGYT	VQFN	RGY	16	250	180.0	12.5	3.71	4.21	1.11	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



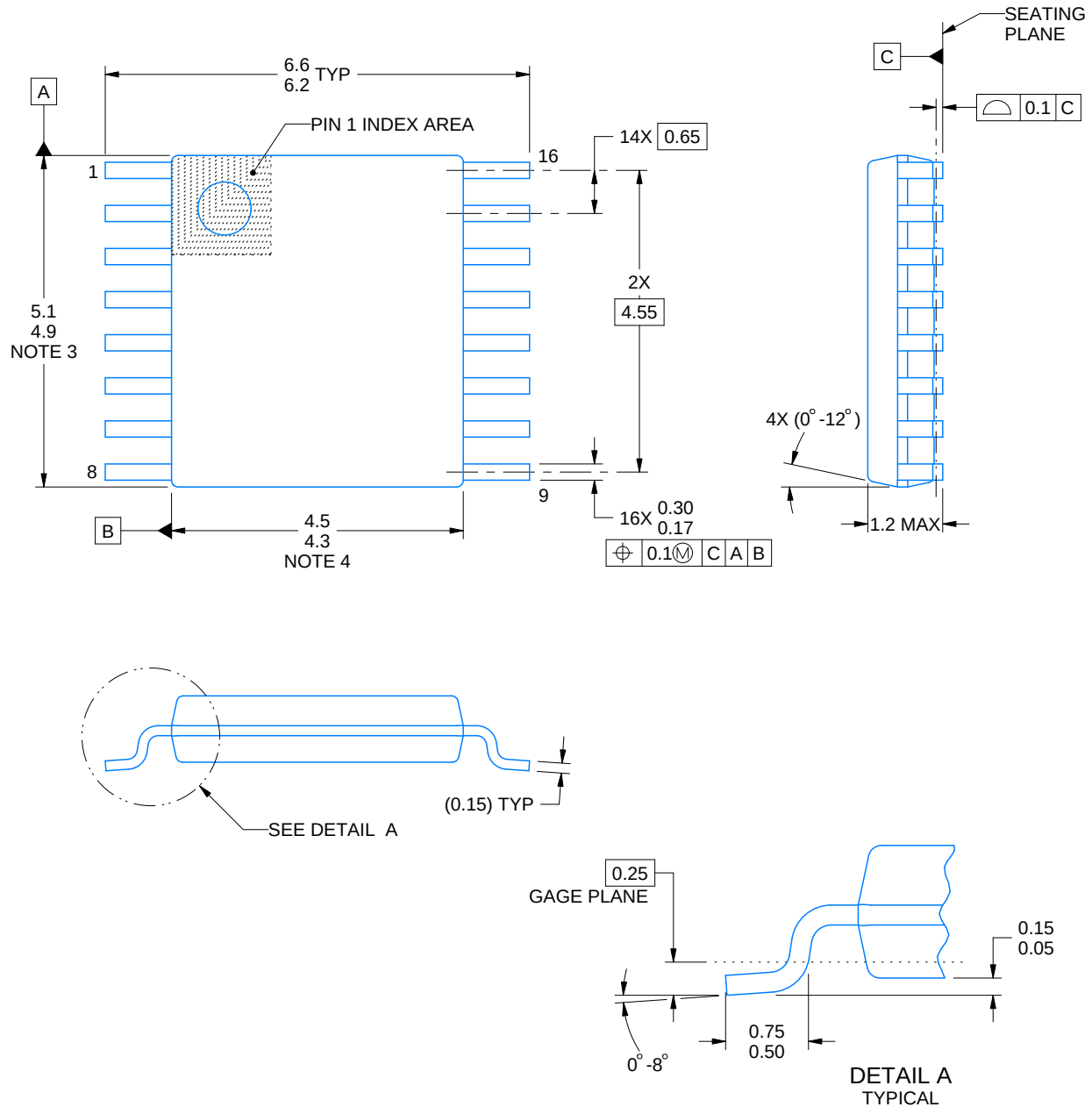
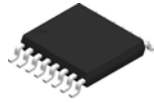
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS40195PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
TPS40195RGYR	VQFN	RGY	16	3000	353.0	353.0	32.0
TPS40195RGYR	VQFN	RGY	16	3000	338.0	355.0	35.0
TPS40195RGYT	VQFN	RGY	16	250	213.0	191.0	35.0
TPS40195RGYT	VQFN	RGY	16	250	338.0	355.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TPS40195PW	PW	TSSOP	16	90	530	10.2	3600	3.5
TPS40195PW.A	PW	TSSOP	16	90	530	10.2	3600	3.5
TPS40195PWG4	PW	TSSOP	16	90	530	10.2	3600	3.5
TPS40195PWG4.A	PW	TSSOP	16	90	530	10.2	3600	3.5



4220204/B 12/2023

NOTES:

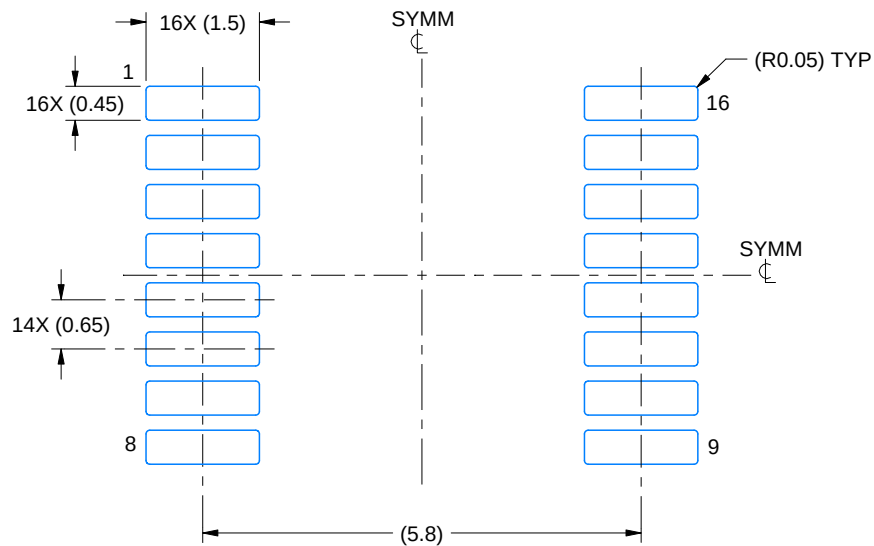
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

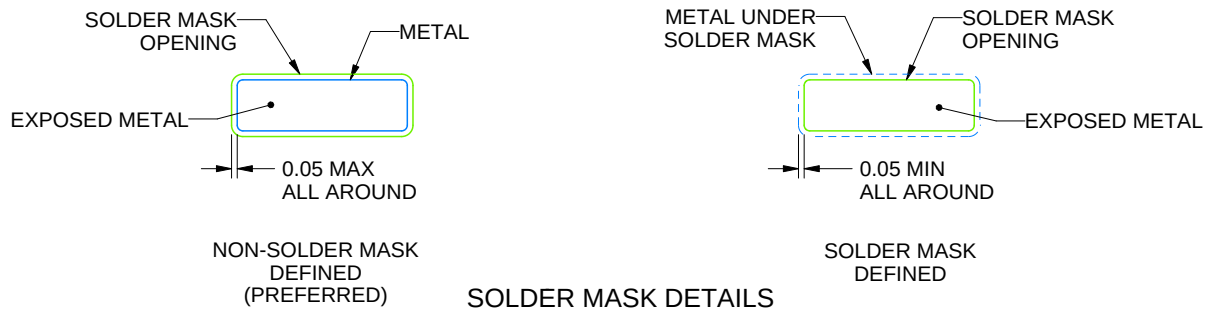
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

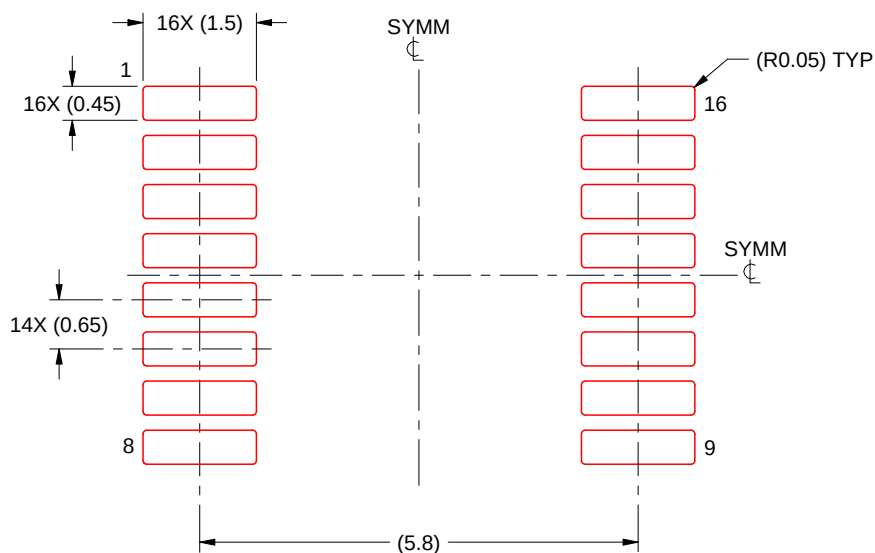
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

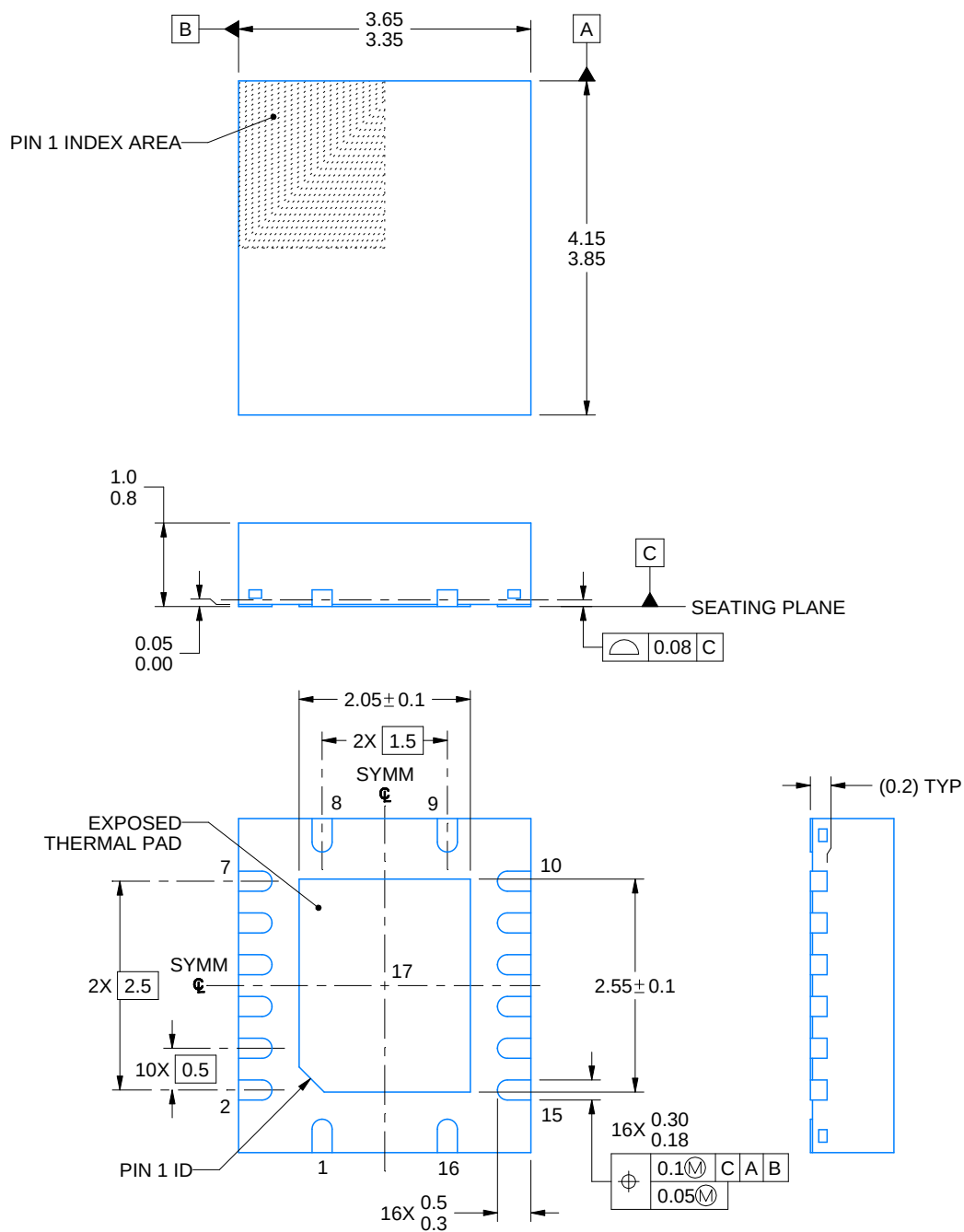
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4225140/A 07/2019

NOTES:

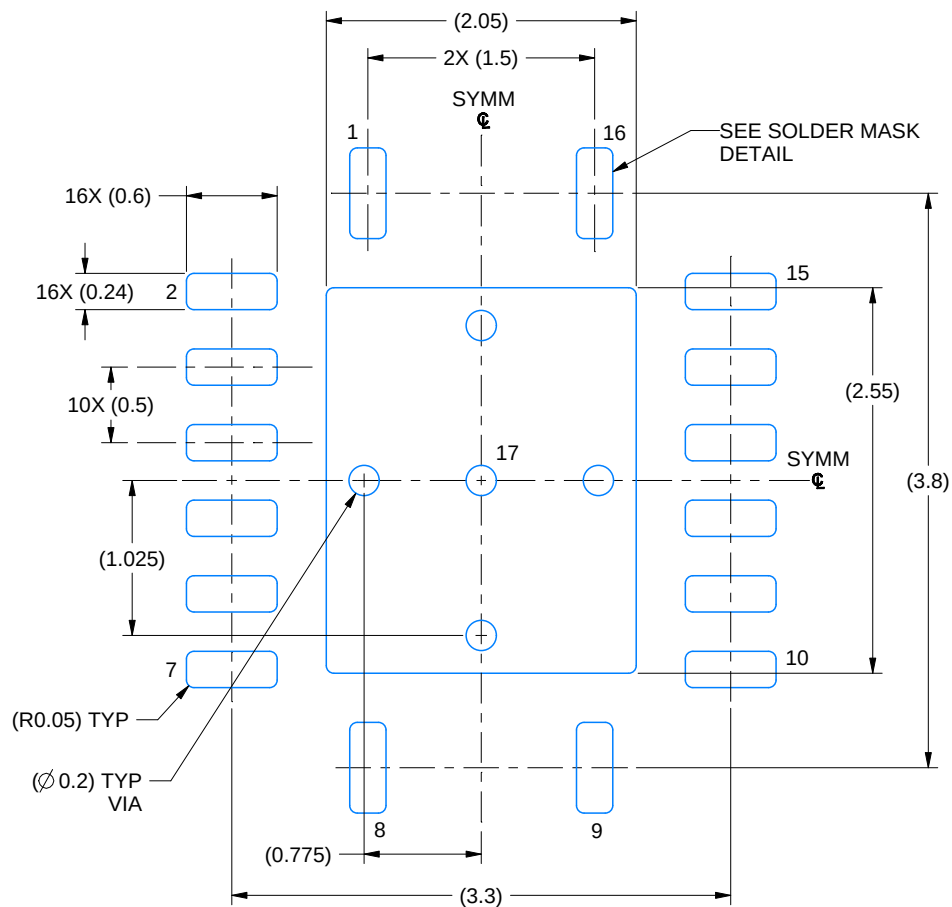
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

RGY0016A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



4225140/A 07/2019

NOTES: (continued)

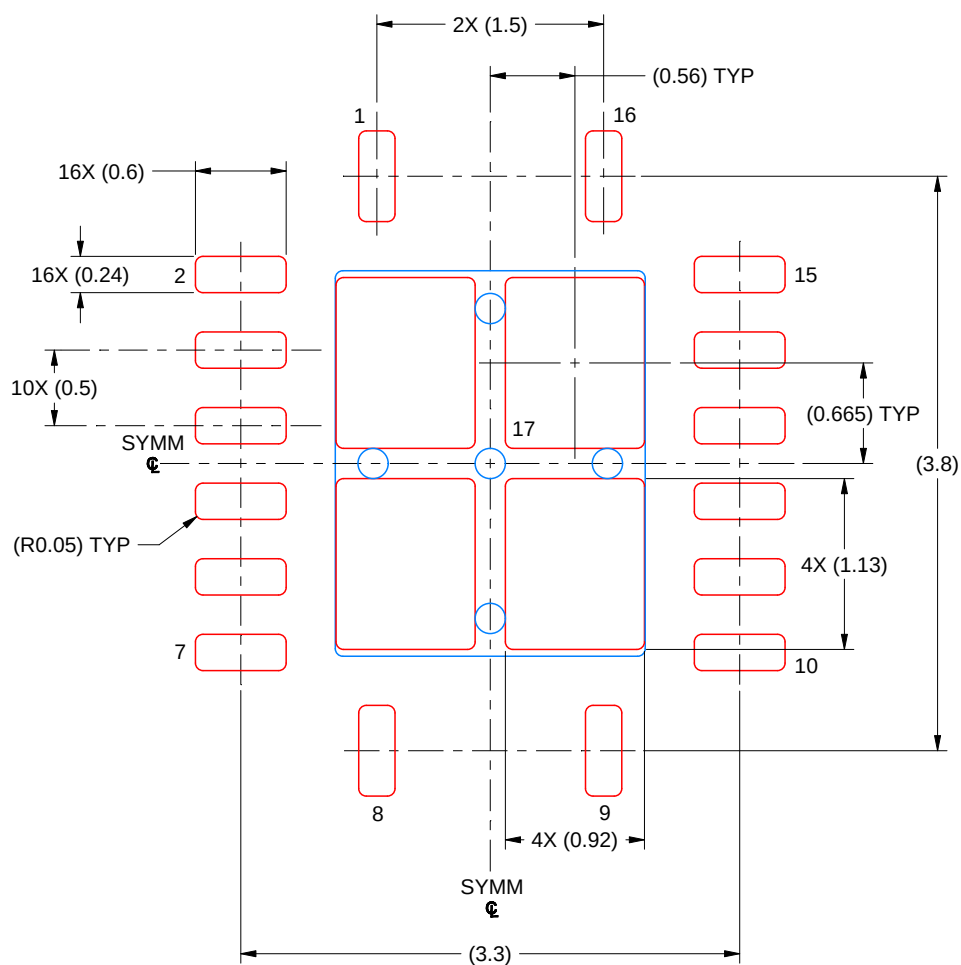
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGY0016A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 17
80% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4225140/A 07/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要通知和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、与某特定用途的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他安全、安保法规或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。对于因您对这些资源的使用而对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，您将全额赔偿，TI 对此概不负责。

TI 提供的产品受 [TI 销售条款](#)、[TI 通用质量指南](#) 或 [ti.com](#) 上其他适用条款或 TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。除非德州仪器 (TI) 明确将某产品指定为定制产品或客户特定产品，否则其产品均为按确定价格收入目录的标准通用器件。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

版权所有 © 2026，德州仪器 (TI) 公司

最后更新日期：2025 年 10 月